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## ABSTRACT

**Method, device, computer-readable storage medium and computer program element for the monitoring of a manufacturing process of a plurality of physical objects**

In the case of the method, an analysis is performed by using values of at least one process parameter of the manufacturing process of the physical object and, as a result of the analysis, when they satisfy a prescribed selection criterion, physical objects are marked in such a way that the associated physical objects can be taken as a random sample for the monitoring of the manufacturing process.

**List of designations**

- 100 — schematic block diagram of a setup of a semiconductor production installation
- 101 — block of an overall manufacturing process
- 102 — block of a first production area
- 103 — block of a second production area
- 104 — block of a third production area
- 105 — block of a fourth production area
- 200 — semiconductor chip production installation
- 201 — multiplicity of semiconductor chip production sub-installations
- 202 — path of a wafer or a lot through the semiconductor chip production installation
- 201 — machine
- 301 — sensor
- 302 — SECS interface
- 303 — PDSF file
- 304 — log file
- 306 — local communication network (LAN)
- 307 — memory
- 308 — evaluation unit
- 409 — mean value of the misalignment values of a lot
- 410 — variation of the distribution
- 411 — wafer close to the mean value of the distribution
- 412 — wafer at the maximum distance from the mean value
- 413 — wafer at the border of the  $1\sigma$  range of the distribution